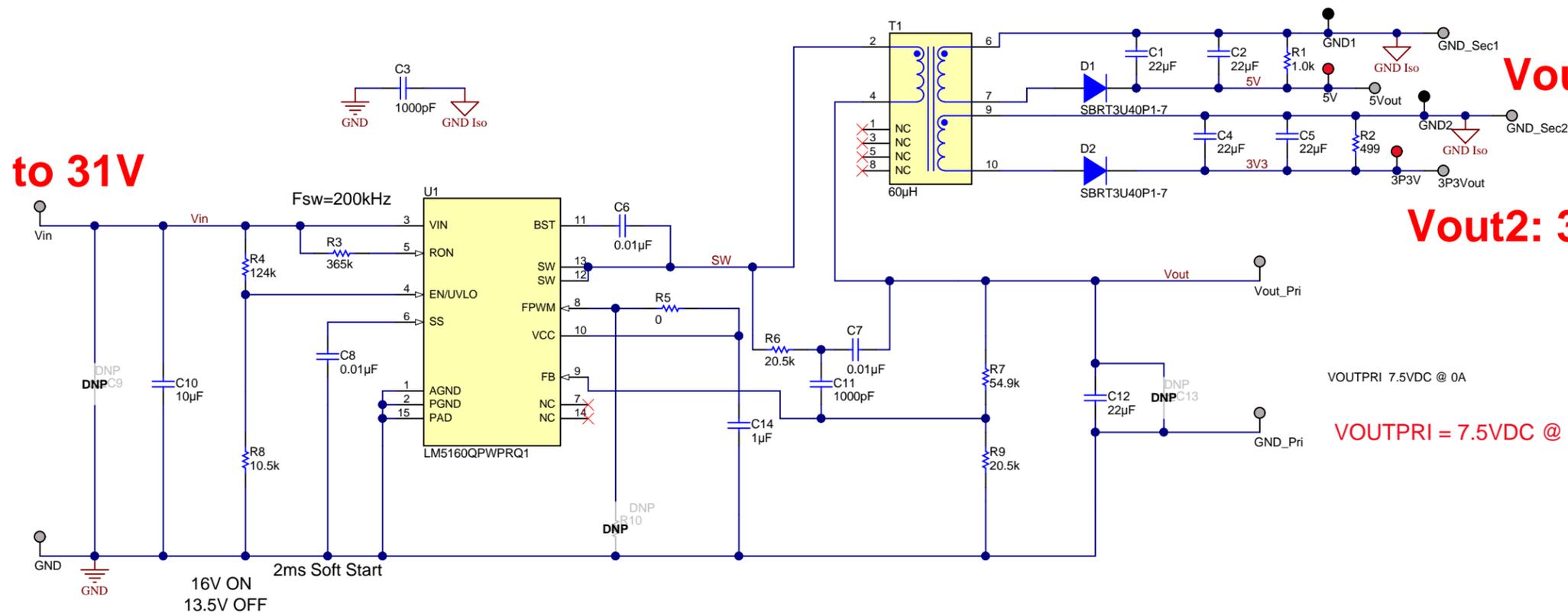


Vin: 18V to 31V

Vout1: 5V @ 0.5A

Vout2: 3.3V @ 1A

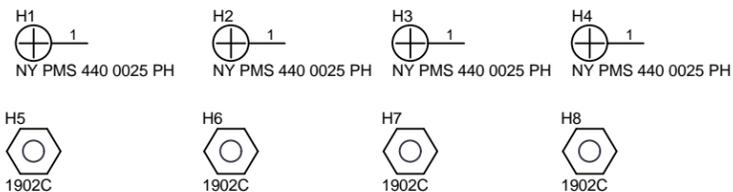
VOUTPRI = 7.5VDC @ 0A



The PCB is configured for Flyback-boost topology, when testing the design, place input GND at -Vout turret.

Orderable: N/A	Designed for: Public Release	Mod. Date: 12/20/2016
TID #: PMP20330	Project Title: LM5160 Dual Output Flyback	
Number: PMP20330	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: PMP20330_Flyback_REVA.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	

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PCB Number: PMP20330
PCB Rev: A

Label Table	
Variant	Label Text
001	

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/15/2016
TID #: PMP20330	Project Title: LM5160 Dual Output Flyback	
Number: PMP20330	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: PMP20330_REVA_Hardware.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	

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